

# W99802G Data Sheet



## MOBILE MULTIMEDIA PROCESSOR

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## 1. GENERAL DESCRIPTION

W99802G is a highly integrated, low-power and high performance MPEG-4 audio/video chip with embedded memory for multimedia cellular phones. It contains a 32-bit ARM CPU, Sensor ISP, JPEG image codec, MPEG-4 video codec, Audio engine, 2-D graphics engine, video processing engine, display controller, USB 1.1 device controller, and flash memory card interface.

W99802G supports 8-bit YCbCr or 10-bit raw data RGB CMOS / CCD sensor interface and provides advanced AEC / AWB / AFC algorithm to deliver professional photo image quality. The supported image resolution can be up to 3M pixels.

The JPEG image codec is compliant with ISO/IEC 10918-1 baseline standard and JFIF format. It is capable of encoding or decoding 30fps JPEG pictures at VGA resolution.

The MPEG-4 video codec is compliant with ISO/IEC 14496-2 Visual standard Simple Profile Level 3. It can also support H.263 short header mode for the implementation of 3GP movie. The video codec supports smart bit rate control and performs up to 30fps VGA simultaneous encode and decode for video conferencing applications.

The audio engine integrates a single channel 16-bit ADC, as well as audio control interface for external audio codec or melody chip. W99802G can provide voice recorder and high quality MP3 and AAC music playback.

The 2-D graphics engine is used for MMI and JAVA acceleration.

The video processing engine is used for the image / video data processing. It can provide versatile functions for image / video capture and playback such as sticker, rotation, color effects, etc.

The display controller can support dual LCM display and bypass mode. The supported LCM can be up to 262K colors.

The USB device controller is compliant with USB1.1 specification and can support configurable pipes for rich USB functions such as Mass storage, PC camera, Virtual COM port and PictBridge.

The flash memory card interface can support embedded NAND type flash and SD / mini-SD / MMC / RS-MMC / T-Flash for storing multimedia data. The file system is FAT compatible and can be accessed by host through host interface.

The internal 32-bit ARM CPU handles audio/video synchronization, file system and all multimedia functions such as still camera, video camcorder, MP3 player and voice recorder according to the high-level commands from host. The host driver programmer can control W99802G without knowing its register programming to shorten the development cycle.

## 2. FEATURES

### CPU

- Built-in 32-bit ARM CPU with I-cache and D-cache.
- Programmable with CPU operating frequency from 200KHz to 166MHz.
- Program code can be downloaded into program buffer through Host Interface or JTAG port.
- Integrate JTAG port to support real time, non-stop ICE function for system development and debug.

### Sensor Interface and ISP

- Support up to 3M pixels CMOS / CCD image sensor.



- Support 8-bit CCIR-656 YCbCr or 10-bit raw RGB Bayer input format.
  - Support both master mode and slave mode sensors.
  - Support universal serial interface to program CMOS / CCD image sensor.
  - Support 30fps real-time preview.
  - Support sensor ISP for color image processing:
    - Black Level Clamping
    - Missing Color Interpolation
    - Auto Exposure Control (AEC)
    - Auto White Balance Control (AWB)
    - Auto Focus Control (AFC)
    - Bad Pixel Concealment
    - Flash Light Control
    - Lens Shading Compensation
    - False Color Suppression
    - Edge Enhancement
    - Color Correction
    - Gamma Correction
    - Contrast Stretching / Hue / Saturation Adjustment
  - Support complete software utilities for sensor module calibration.
- **Video Processing Engine**
- Support hardware image sticker function for both preview and compression data.
  - Support real-time hardware flip / mirror / rotation (90, 180 and 270 degree) function.
  - Support special image color effect functions such as B&W, Negative, Sepia, Oil, Emboss, Binary, etc.
  - Support linear scaling down from 1 ~ X/256 with 2D filter for better image quality.
  - Support YUV-to-RGB and RGB-to-YUV Color Format Conversion and Data Format Transformation for video display and image editing.
- **MPEG-4 Video Codec**
- Support MPEG4 Simple Profile Level 3 compression tools and compliant with ISO/IEC 14496-2 Visual Standard.
  - Support I-VOP and P-VOP.
  - Support motion estimation with 16×16 search range and half pixel resolution.
  - Support AC/DC prediction, 4 motion vectors per macro block, unrestricted motion compensation.
  - Support RVLC and Data Partitioning for error resilience.
  - Support Short Header Mode (H.263 baseline).
  - Support real-time 30fps video compression/decompression up to VGA resolution.
  - Support smart bit rate control and simultaneous encode/decode for video conferencing application.



## ❑ **JPEG Image Codec**

- Compliant with ISO/IEC 10918-1 internal JPEG standard.
- Support resolution up to 3M pixels and capable of encoding or decoding 30fps real-time VGA JPEG.
- Support YUV 4:2:2 and 4:2:0 formats encode.
- Support YUV 4:4:4, 4:2:2 and 4:2:0 formats decode.
- Support programmable quantization table.
- Support programmable Huffman table decoding.
- Capable of decoding JPEG image with specified rectangle to a specified size.
- Support resolution scaling up and 1× ~ 8× linear digital zoom.
- Support JPEG resizing and trimming.
- Support thumbnail image.
- Support JPEG Exchangeable Image File (EXIF) format.

## ❑ **Audio Engine**

- Support I2S codec interface to connect with external audio codec.
- Support audio control interface for external melody chip
- Integrate a 16-bit ADC for microphone analog input
- Support MP3 / AMR-WB decoder.
- Support AAC-LC / AMR-NB / ADPCM codec.

## ❑ **2-D Graphics Engine**

- Support 8/16/32-bpp graphics modes.
- Support 5 Bit Block Transfer (BLT) function with ROP function.
  - Write BitBLT
  - Read BitBLT
  - Copy BitBLT
  - Pattern Fill BitBLT
  - Solid Fill BitBLT
- Hardware Clipper.
- Tile BLT.
- Mono-to-Color Expansion for text output acceleration.
- Transparency Control (Sprites).
- Image Blending (Semi-Transparency).
- Bit Plane Mask.
- Programmable 2D filter functions for special color effects.
- Support Bresenham Line and Frame Drawing.

## ❑ **Display Controller**

- Support 8/12/16/18-bit RGB data output interface to connect with 80/68 series MPU type LCM module.
- Support LCM resolution up to 240×320.
- Support dual LCM control for MPU interfaced LCM.



- Support LCM bypass mode that allows the host to access LCM directly while W99802G is in suspend mode.
  - Support RGB444 (4K colors), RGB565 (65K colors) and RGB666 (262K colors) color formats for display output.
  - Support 8/16/32-bit graphics mode OSD.
  - Support graphics / video overlay using color key and alpha blending control.
  - Support playback pan / tilt / zoom.
  - Support CCIR-656 8-bit YUV output for external TV encoder.
  - Support picture-in-picture display for video conferencing applications.
- **USB Device Controller**
- Compliant with USB 1.1 specification.
  - Support four USB pipes including one control pipe and 3 configurable pipes for rich USB functions.
  - Support USB Mass Storage.
  - Support USB PC Camera (DirectShow).
  - Support USB Virtual COM Port with modem capability.
  - Support USB PictBridge.
- **Memory Card Interface**
- Support NAND Type flash.
  - Support SD, mini-SD, MMC, RS-MMC, and T-Flash.
- **Host Bus Interface**
- Support 8/9/16/18-bit parallel slave interface to connect with 80 or 68 series host MPU.
  - Support bypass mode to allow the host to access the LCM and melody chip directly.
  - Support DMA data transfer between host MPU and W99802G.
  - Allow host to access W99802G memory buffer and control registers.
- **Peripheral Support**
- Support two Timers and one programmable 24-bit Watch-Dog timer.
  - Supports universal synchronous serial interface for connecting with synchronous serial device.
  - Support GPIOs for system control.
- **J2ME MIDP 2.0 Graphics / Game native layer acceleration**
- **Multimedia File Format Support**
- 3GP (H.263+AMR-NB)
  - MP4 (MP4+AAC-LC)
  - AVI
  - ASF
- **Flash File System Support**
- Support FAT12/16/32



- Support long filename.
- **Power Supply**
  - Host Interface: 1.8V - 3.3V
  - I/O Power Supply:
    - General Digital I/O: 2.5V – 3.3V
    - USB Transceiver: 3.0V – 3.3V
    - Audio ADC: 2.5V – 3.3V
- **Package: LFBGA 184-Balls package (10mm x 10mm), Lead-free.**



### 3. PIN DESCRIPTION

#### 3.1 W99802G Pin Definition

The following signal types are used in these descriptions.

##### 3.1.1 Pin Type Definition

TYPE	DESCRIPTION
I	Input pin
IS	Input pin with Schmitt trigger
B	Bi-directional input/output pin
BU	Bi-directional input/output pin with internal pull-up
BD	Bi-directional input/output pin with internal pull-down
O	Output pin
A	Analog input/output pin
P	Power supply pin
G	Ground pin
#	Active low

##### 3.1.2 Pin List

###### USB Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
DP	B1	A	USB DP (D+) Signal
DM	D2	A	USB DM (D-) Signal
USBVDD	D18	P	USB Power Supply +3.3V ± 0.3V.
USBVSS	E7	G	USB Ground.

###### Sensor or Video Input Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
SVID[1:0] / GPIOA[1:0]	J6, N1	BD	Sensor Data Input [1:0] GPIO Function : GPIOA[1:0]
SVID[9:2]	K18, L6, G18, R1, J18, N2, P1, K6	ID	Sensor Data Input [9:2]
SPCLK	P2	ID	Clock Input from Sensor for Pixel Data
SVS	R2	BD	Vertical Sync.
SHS	N18	BD	Horizontal Sync.
SCLK	L5	O	Clock Output to Sensor



Sensor or Video Input Interface, continued

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
SCK / GPIOA[2]	T1	BU	Serial Interface Clock GPIO Function: GPIOA[2]
SDI/SDA / GPIOA[3]	L13	BU	Serial Data Input/ Serial Data Acknowledge GPIO Function: GPIOA[3]
SDO/SDE / GPIOA[4]	L14	BU	Serial Interface Data Output / Serial Data Enable GPIO Function: GPIOA[4]

### Audio Digital Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
ASCLK / GPIOA[8]	F2	BU	Audio Interface: Audio System Clock GPIO Function: GPIOA[8]
ADO / GPIOA[9]	M18	BU	Audio Interface: I2S=> Audio Data Output GPIO Function: GPIOA[9]
AWS / GPIOA[10]	F1	BU	Audio Interface: I2S=> Audio Word Select GPIO Function: GPIOA[10]
ABCLK / GPIOA[11]	G5	BD	Audio Interface: I2S=> Audio Bit Clock Output GPIO Function: GPIOA[11]
ADI / GPIOA[12]	F8	BD	Audio Interface: I2S=> Audio Data Input GPIO Function: GPIOA[12]
ARST# / GPIOA[13]	E1	BD	Audio Interface: Audio Reset GPIO Function: GPIOA[13]

### Audio Analog Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
CAD1	B2	A	Decoupling for ADC
MIC_IN	A2	A	Audio (Microphone) Input
MIC_BIAS	B17	A	Microphone Bias
VREFC	B18	A	ADC Reference Voltage
ADO_AVDD	A17	P	Audio ADC Analog Power Supply +3.3V
ADO_AVSS	B15	G	Audio ADC Analog Ground
ADO_DVDD	J13	P	Audio Digital Power Supply
ADO_DVSS	C1	G	Audio Digital Ground

**JTAG Interface Pins**

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
TCK	U12	ID	JTAG Test Clock
TMS	V16	IU	JTAG Test Mode Select
TDI	V12	IU	JTAG Test Data in
TDO	U11	O	JTAG Test Data out
TRST#	V11	IU	JTAG Reset

**UART Interface Pins**

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
RTS# / GPIOA[16]	K14	BD	Request To Send / GPIO Function: GPIOA[16]
DTR# / GPIOA[17]	N5	BD	Data Terminal Ready GPIO Function: GPIOA[17]
SOUT / GPIOA[18]	K17	BD	Serial Data Output (TXD) GPIO Function: GPIOA[18]
CTS# / GPIOA[19]	U2	BD	Clear To Send GPIO Function: GPIOA[19]
DSR# / GPIOA[20]	U5	BD	Data Set Ready GPIO Function: GPIOA[20]
RLSD# / GPIOA[21]	U4	BD	Receive Line Signal Detect GPIO Function: GPIOA[21]
RI# / GPIOA[22]	L18	BD	Ring Indicator GPIO Function: GPIOA[22]
SIN / GPIOA[23]	M14	BD	Serial Data Input (RXD) GPIO Function: GPIOA[23]
SOUT2 / GPIOA[24]	V2	BD	Serial Data Output –2 (High Speed TXD) GPIO Function: GPIOA[24]
SIN2 / GPIOA[25]	U1	BD	Serial Data Input – 2 (High Speed RXD) GPIO Function: GPIOA[25]



## LCM Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
LCLK / LA0	H13	BD	Clock Input for output Data to TV encoder LCM Interface (O): Address-0, R/S# (CMD/DAT#)
LCLKO / LCS0#	H5	O	Clock for Digital Display Data Output LCM Interface : LCD Chip Select-0
LCS1# / GPIOB[17]	G1	BU	LCM Interface : LCD Chip Select-1 GPIO Function : GPIOB[17]
LWR# / LR/W#/ LHSYNC	H1	O	LCM 80-series interface: Write Enable, Active Low LCM 68-series interface: "1" => Read, "0"=> Write Horizontal Sync to TV encoder
LRD# / LE / LVSYNC	G17	O	LCM 80-series interface: Read Enable, Active Low LCM 68-series interface: Data Enable, Active High Vertical Sync to TV encoder
LDAT [7:0]	L1, H17, L2, J17, M1, H6, M2, H18	BU	LCM Data Bus / TV-encoder Data Bus Bit-7_0
LDAT [15:8] / GPIOB[7:0]	H2, J5, H14, K5, K1, J2, J14, K2	BU	LCM Data Bus Bit-15_8 GPIO Function : GPIOB[7:0]
LDAT [17:16] / GPIOB[9:8]	G2,J1	BU	LCM Data Bus Bit-17_16 GPIO Function : GPIOB[9:8]
LCS2# / GPIOB[16]	G14	BU	MCU Interface : LCD Chip Select 2 GPIO Function : GPIOB[16]

**Memory Bus Interface**

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
MSCE#	E8	BU	Memory Slave (I) : Chip Enable Signal
MSA3	B6	BU	Memory Slave (I) : Address – 3
MSWR# / MSR/W#	A5	BU	Memory Slave 80 (I): Write Enable Signal Memory Slave 68 (I): Read/Write Control
MSRD# / MSE	E10	BU	Memory Slave 80 (I): Read Enable Signal Memory Slave 68 (I): Data Enable
MSA[2:0]	F17, A4, B14	BD	Memory Slave (I): Address MSA[2:0]
MSD[7:0] /	F11, B9, F10, A8, E17, A7, E11, B7	BD	Memory Slave (I): Data Bus Bit-7_0
MSD[15:8] / GPIOB[31:24]	F14, A11, B11, A10, D17, B10, E12, A9	BD	Memory Slave (I): Data Bus Bit-15_8 GPIO Function: GPIOB[31:24]
MSD[16] / GPIOB[18]	B8	BD	Memory Slave (I): Data Bus Bit-16 GPIO Function : GPIOB[18]
MSD[17] GPIOB[19]	A6	BD	Memory Slave (I) : Data Bus Bit-17 GPIO Function : GPIOB[19]



## NAND / SD / MMC Memory Card Interface

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
SCS0# / GPIO[0]	P13	BU	NAND Flash Interface =>(O): Chip-0 Enable GPIO Function: GPIO[0]
SCS1# / SD_CLK / GPIO[1] / MMC_CLK	V14	BU	NAND Flash Interface =>(O): Chip-1 Enable SD : Clock GPIO Function: GPIO[1] MMC : Clock
SALE / GPIO[2]	U18	BU	NAND Flash Interface => (O): Address Latch Enable GPIO Function: GPIO[2]
SCLE / GPIO[3]	U10	BU	NAND Flash Interface => (O): Command Latch Enable GPIO Function: GPIO[3]
SWE# / GPIO[4]	P9	BU	NAND Flash Interface => (O): Write Enable GPIO Function: GPIO[4]
SRE# / GPIO[5]	U9	BU	NAND Flash Interface => (O): Read Enable GPIO Function: GPIO[5]
SRB# / GPIO[6]	T18	BU	NAND Flash Interface => (I): Ready/Busy Signal GPIO Function: GPIO[6]
SWP# / GPIO[7]	V9	BU	NAND Flash Interface => (O): Write Protect GPIO Function: GPIO[7]
SD[0] / SD_DAT0 / GPIO[8]/ MMC_DO	N11	BU	NAND Flash Interface => (I/O): Data Bus Bit-0 SD : Data-0 GPIO Function: GPIO[8] MMC : Data-Out
SD[2:1] / SD_DAT[2:1] / GPIO[10:9]	R17,V8	BU	NAND Flash Interface => (I/O): Data Bus Bit-2_1 SD : Data-2:1 GPIO Function: GPIO[9]
SD[3]/ SD_DAT[3] / GPIO[11]/ MMC_CS#	U8	BU	NAND Flash Interface => (I/O): Data Bus Bit-3 SD : Data-3 GPIO Function: GPIO[10] MMC : Chip Select
SD[4] SD_CMD / GPIO[12]/ MMC_DI	N10	BU	NAND (I/O): Data Bus Bit-4 SD : Command GPIO Function: GPIO[11] MMC : Data-In
SD[7:5] / GPIO[15:13]	U7, N9, V7	BU	NAND Flash Interface => (I/O): Data Bus Bit-7_5 GPIO Function: GPIO[15:12]



## GPIO Pins

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
GPIO[0] / HGPIO[0] / PCLK-A	V5	BU	General Purpose I/O [0] Programmable Clock Output-A (PWM Function)
GPIO[1] / HGPIO[1] / MSRDYO	A12	BU	General Purpose I/O [1] Force GPIO[1] to low state.
GPIO[2] / HGPIO[2] / FL_TRG	P11	BD	General Purpose I/O [2] Flashlight Trigger Control
GPIO[3] / HGPIO[3] / MSINTO	P18	BD	General Purpose I/O [3]
GPIO[5:4] / HGPIO[5:4] / FEINT[1:0]	P17, U6	BU	General Purpose I/O [5:4] Fast External Interrupt Input [1:0]
GPIO[7:6] / HGPIO[7:6] / FEINT[3:2]	R18, V6	BD	General Purpose I/O [7:6] Fast External Interrupt Input [3:2]
GPIO[8]	E18	BD	General Purpose I/O [8]
GPIO[9]	E2	BD	General Purpose I/O [9]
GPIO[10]	D1	BD	General Purpose I/O [10]
GPIO[11]	F18	BD	General Purpose I/O [11]
GPIO[12] USK	V3	BU	General Purpose I/O [12] Universal Serial Interface (USI): USK
GPIO[13] / UDI	P7	BU	General Purpose I/O [13] Universal Serial Interface (USI): UDI
GPIO[14] / UDO	V4	BU	General Purpose I/O [14] Universal Serial Interface (USI): UDO
GPIO[15] / UCS0	N8	BU	General Purpose I/O [15] Universal Serial Interface (USI) : UCS0
GPIO[16] / UCS1	P10	BU	General Purpose I/O [16] Universal Serial Interface (USI) : UCS1
GPIO[17] / CLK_IN2	N17	BU	General Purpose I/O [17] Clock-2 Input Pin
GPIO[18] / STDBY	L17	BD	General Purpose I/O [18] System Standby Flag STDBY Output
GPIO[19] / PCLK-B	M17	BD	General Purpose I/O [19] / Programmable Clock Output-B (PWM Function)

**Miscellaneous**

PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
XIN	V13	I	Reference clock input from crystal or clock source.
XOUT	U13	O	Oscillator output to a crystal. This pin is left unconnected if an external clock source is used.
TME	U14	ID	Test Mode Enable. Only for test, this pin must be connected to GND for normal operation.
RST#	U17	IS	Reset In. This pin is active low to reset chip.
S2_PWR	A3	O	Power Plate Control Section 2.

**Power and Ground**

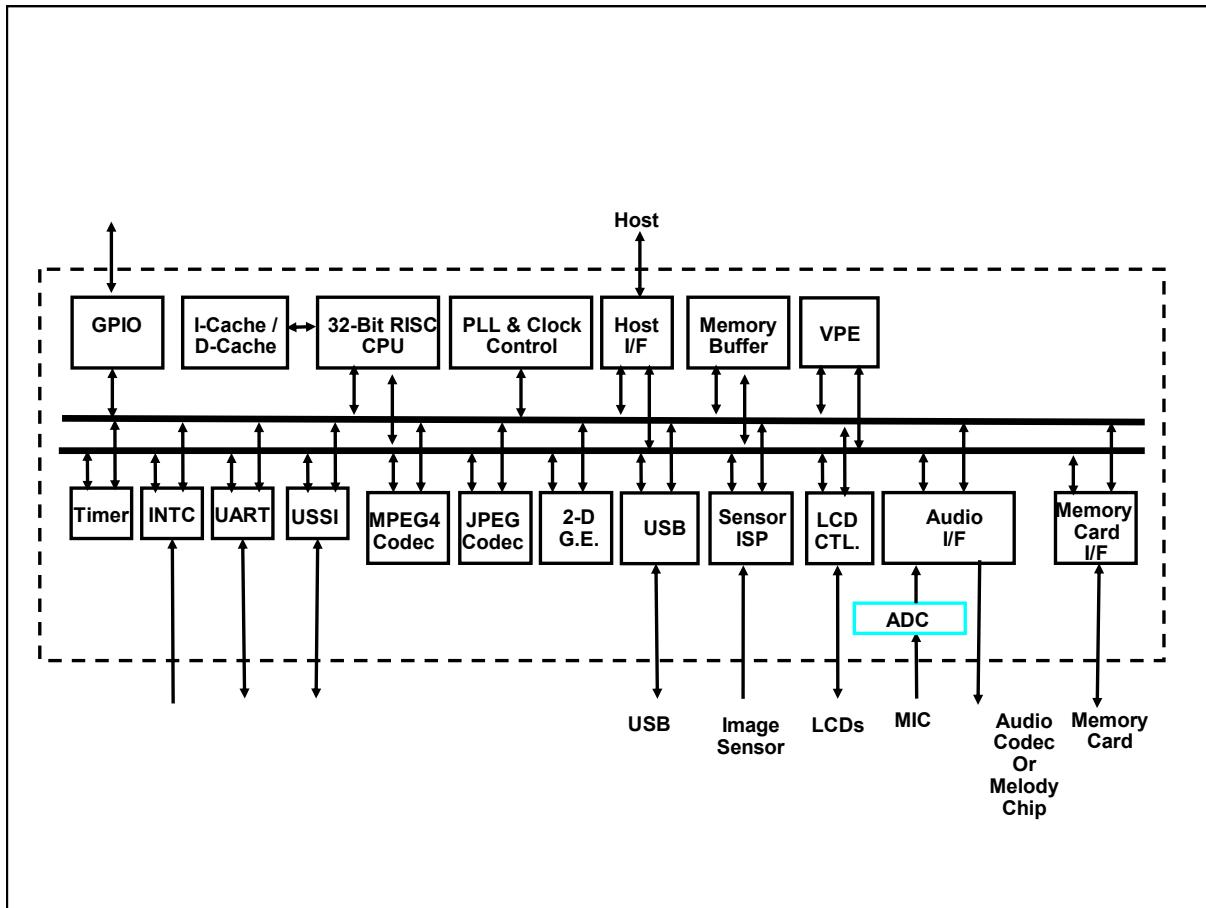
PIN NAME	PIN NUMBER	TYPE	DESCRIPTION
VCC	F5, F9, M5, N14, P8, B5	P	I/O Pad Buffer Power Supply (2.5V~3.3V)
VCC_LCM	C18, E13	P	I/O Pad Buffer to Frame buffer Power Supply (2.6V~3.3V)
VCC_HIC	B12	P	HOST BUS Interface Buffer Supply (1.8V~3.3V)
GND	F12, F13, F6, F7, G13, G6, K13, M13, M6, N12, N13, N6, N7, V17, B4, A16	G	Ground.
VDDHI	B13	P	Internal Core Logic Power Supply
VDDI	E9, P12, P6, E6, A15	P	Internal Core Logic Power Supply
AVDDP	V15	P	PLL Power Supply
AVSSP	U15	G	PLL Ground
FB_VCC	A13, A14	P	Frame Buffer Power Supply (2.6V ~ 3.3V)
VPRO	V10	ID	NC



### 3.2 W99802G Pin Assignment (Bottom View)

18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	•∠
D	ADO_AVDD	GND	VDD1	FB_VCC	FB_VCC	HGPIO1	MSD14	MSD12	MSD8	MSD4	MSD2	msd17	mswR#	MSA1	S2PWR	MIC_IN	D	A
VRE_FC	MIC_BIAS		ADO_AVSS	MSA0	VDDHI	VCC_HIC	MSD13	MSD10	MSD6	msd16	MSD0	msa3#	VCC	GND		CADI	DP	B
VCC_LCM																	ADO_DVSS	C
USB_VDD	MSD11															DM	GPIO_10	D
GPIO8	MSD3			D	VCC_LCM	MSD9	MSD1	MSRD#	VDDI	msCE#	USB_VSS	CDDI	D			GPI_O9	ARS_T#	E
GPIO_11	MSA2			MSD15	GND	GND	MSD7	MSD5	VCC	ADI	GND	GND	VCC			ASC_LK	AWS	F
SVID7	LRD#			ICS2#	GND							GND	ABC_LK			LDAT_17	LCS_1#	G
LDAT0	LDAT6			LDAT_13	LA0							LDAT2	LCS_0#			LDAT_15	LWR#	H
SVID5	LDAT4			LDAT9	ADO_DVDD							SVID1	LDAT_14			LDAT_10	LDAT_16	J
SVID9	SOUT			RTS#	GND							SVID2	LDAT_12			LDAT8	LDAT_11	K
RI#	GPIO_18			SDO	SDA							SVID8	SCLK			LDAT5	LDAT7	L
ADO	GPIO_19			SIN	GND							GND	VCC			LDAT1	LDAT3	M
shs	GPIO_17			VCC	GND	GND	SD_DAT0	SD_CMD	GPIO14	GPIO_15	GND	GND	DTR#			SVID4	SVID0	N
HGPIO3	HGPIO5			D	FSCS0#	VDDI	HGPIO_2	GPIO_16	GPIO4	VCC	GPIO_13	VDDI	D			SPC_LK	SVID3	P
HGPIO7	SD_DAT2															SVS	SVID6	R
GPIO6																	SCK	T
GPIO2	RST#			AVS_SP	TME	XOUT	TCK	TDO	GPIO3	GPIO5	SD_DAT3	GPIO15	HGPIO4	DSR#	RLSD#	CTS#	SIN2	U
D	GND	TMS	AVD_DP	SD_CLK	XIN	TDI	TRST#	VPRO	GPIO7	SD_DAT1	GPIO13	HGPIO6	HGPIO0	GPIO_14	GPIO_12	SOUT2	D	V

## 4. W99802G BLOCK DIAGRAM





## 5. ELECTRICAL CHARACTERISTICS

### 5.1 Digital Absolute Maximum Ratings

**Table 5-1 Absolute Maximum Ratings**

PARAMETER	MIN.	MAX.	UNIT
Ambient temperature	-20	85	°C
Storage temperature	-40	125	°C
DC supply voltage for core (1.2V) power (VDDI)	0	1.3	V
DC supply voltage for I/O (3.3V) power (VDDB)	0	3.6	V
I/O pin voltage with respect to V <sub>SS</sub>	-0.3	VDDB +0.4	V

**Note:** Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

### 5.2 Digital DC Characteristics

**Table 5-2 DC Characteristics**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>DDB</sub>	Power Supply for I/O Pads		2.6	3.0	3.6	V
USBVDD	Power Supply for USB Transceiver		3.0	3.30	3.6	V
AVDDP	Power Supply for PLL		1.20	1.25	1.30	V
V <sub>DDI</sub>	Power Supply for Core		1.20	1.25	1.30	V
V <sub>IL</sub>	Input Low Voltage		0		0.8	V
V <sub>IH</sub>	Input High Voltage		2.0		VDDB +0.3	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OUT</sub> = 2mA			VSS+0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OUT</sub> = -2mA	2.4			V
I <sub>IL</sub>	Input Low Leakage Current	V <sub>IN</sub> = 0.4V			10	µA
I <sub>IH</sub>	Input High Leakage Current	V <sub>IN</sub> = 2.4V			-10	µA
I <sub>UP</sub>	Pull-up Current	V <sub>IN</sub> = 0V			-500	µA
I <sub>PD</sub>	Power Down Current No load, Host inactivated.			5	10	µA
I <sub>DD</sub>	Active Current 3GP recording, CIF-30fps	V <sub>DDB</sub> =2.8V		15		mA
		V <sub>DDI</sub> =1.2V		60		
Top	Operation Temperature		-20		70	°C



### 5.3 Digital AC Characteristics

#### 5.3.1 Reset AC Characteristics

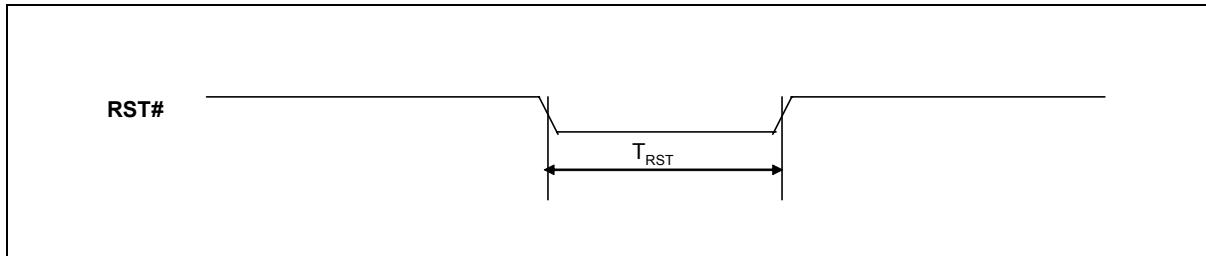


Figure 5-1 Reset Timing Diagram

Table 5-3 Reset Timing

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$T_{RST}$	Reset Pulse Width		10.0		mS

#### 5.3.2 Clock Input Characteristics

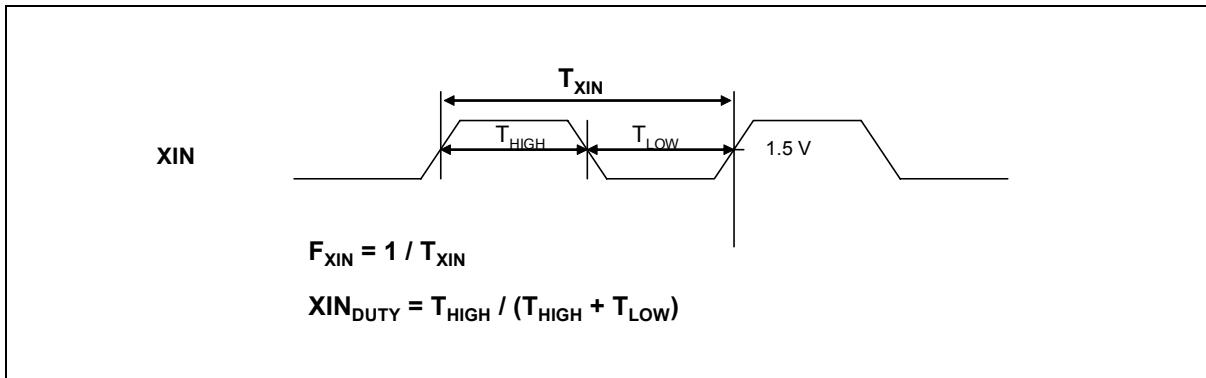


Figure 5-2 Clock Input Timing Diagram

Table 5-4 Clock Input Timing Specification

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$F_{XIN}$	Clock Input Frequency	4	12.0		MHz
$XIN_{DUTY}$	Clock Input Duty Cycle	45	50	55	%
$V_{IL}$ (XIN)	XIN Input Low Voltage	0		0.8	V
$V_{IH}$ (XIN)	XIN Input High Voltage	2.0		$V_{DD} + 0.3$	V

### 5.3.3 Video Input AC Characteristics

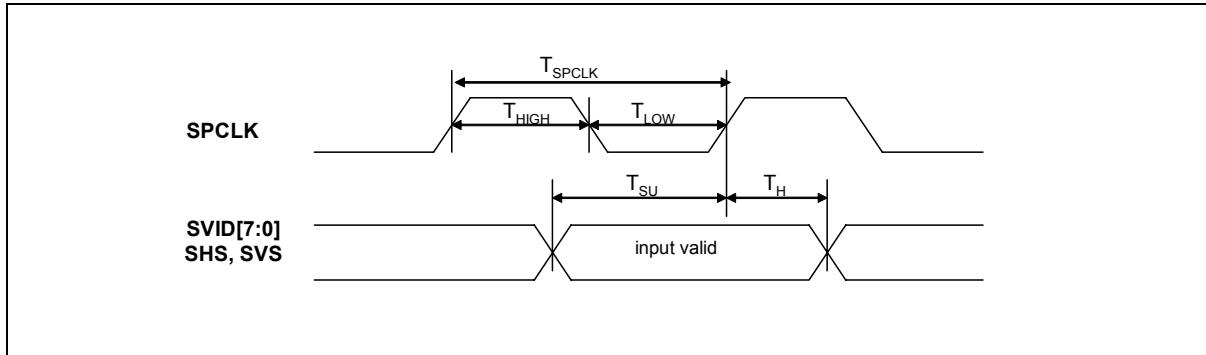


Figure 5-3 Input Video Timing Diagram

**Table 5-5 Input Video Timing**

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
$F_{SPCLK}$	SPCLK Frequency = $1 / T_{SPCLK}$	---	96	MHz
$T_{HIGH}$	SPCLK Clock High Time	8.0	---	ns
$T_{LOW}$	SPCLK Clock Low Time	8.0	---	ns
$T_{SU}$	SVID[9:0], SHS, SVS Setup Time	1.0	---	ns
$T_H$	SVID[9:0], SHS, SVS Hold Time	1.0	---	ns

### 5.3.4 Host Interface: Memory Bus AC Characteristic

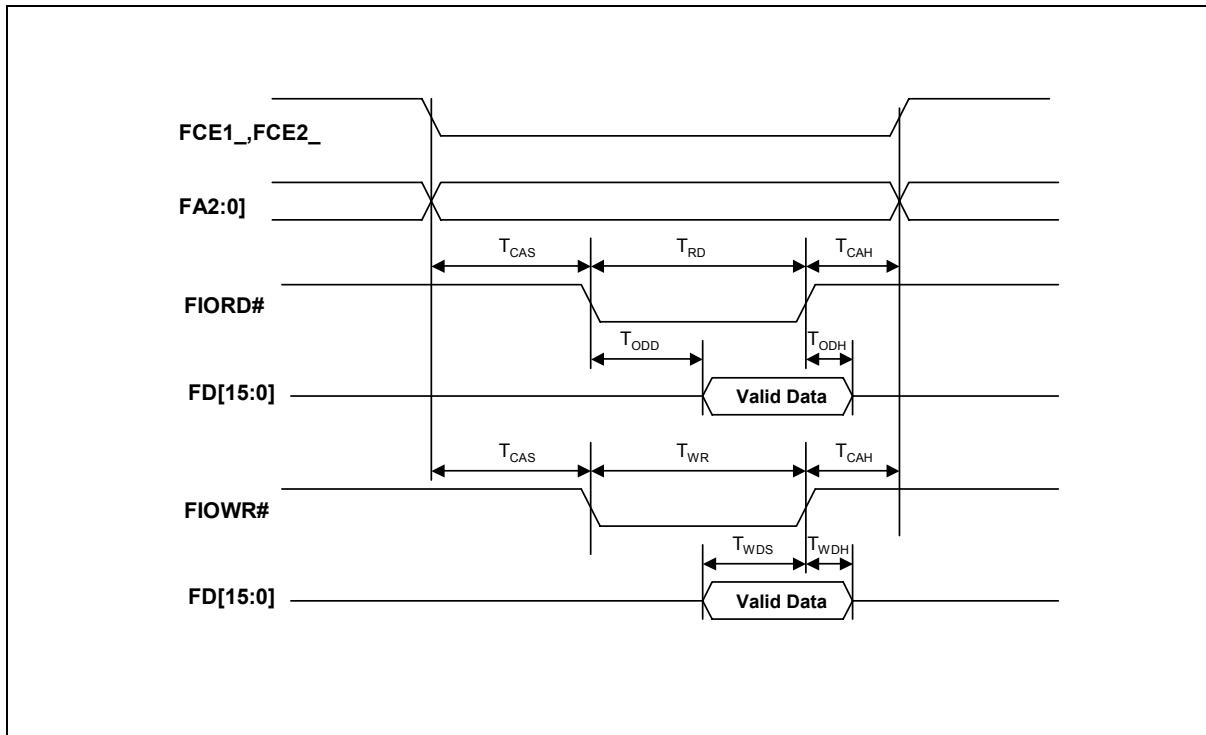


Figure 5-4 Host Interface : Memory Bus Timing Diagram

**Table 5-6 Host Interface: Memory Bus Timing**

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
$T_{CAS}$	Set-up time, FCE1_, FCE2_ and FA valid before FIORD# & FIOWR# low	0	---	ns
$T_{CAH}$	Hold time, FCE1_, FCE2_ and FA valid after FIORD# & FIOWR# high	0	---	ns
$T_{ODD}$	FIORD# Low to Data Valid Delay	---	8.5	ns
$T_{ODH}$	Read Data Output Hold Time	2.65	---	ns
$T_{RD}$	FIORD# Pulse Width	12	---	ns
$T_{WDS}$	Set-up time, FD valid before FIOWR# low	0	---	ns
$T_{WDH}$	Hold time, FD valid after FIOWR# high	0	---	ns
$T_{WR}$	FIOWR# Pulse Width	12	---	ns

### 5.3.5 LCD Interface AC Characteristics

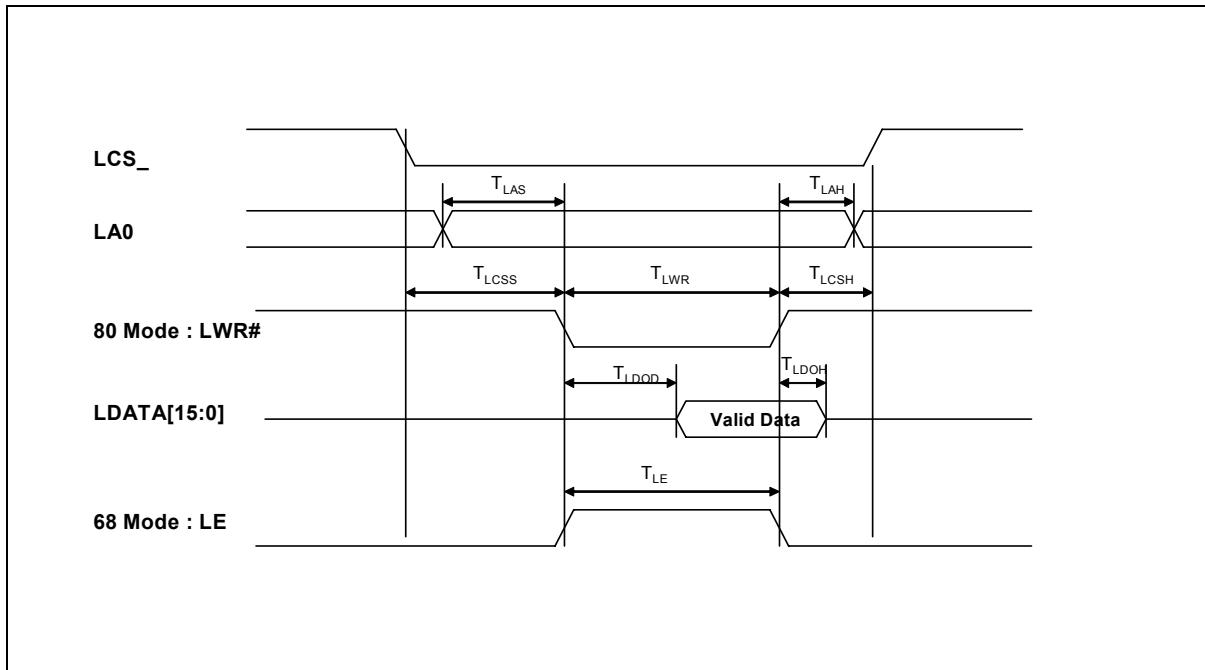


Figure 5-5 LCD Interface Timing Diagram

Table 5-7 LCD Interface Timing

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$T_{LCSS}$	Chip Select Set-up Time		1/2	---	PCLK
$T_{LCSH}$	Chip Select Hold Time		1/2	---	PCLK
$T_{LAS}$	Address Set-up Time		1	---	PCLK
$T_{LAH}$	Address Hold Time		1	---	PCLK
$T_{LDOD}$	Write Data Active Delay		0	1/2	PCLK
$T_{LDOH}$	Write Data Hold Time		1/2	---	PCLK
$T_{LWR}$	LWR# Pulse Width	80 Mode	1/2	---	PCLK
$T_{LE}$	LE Pulse Width	68 Mode	1/2	---	PCLK

### 5.3.6 SD/MMC Host Interface AC Characteristics

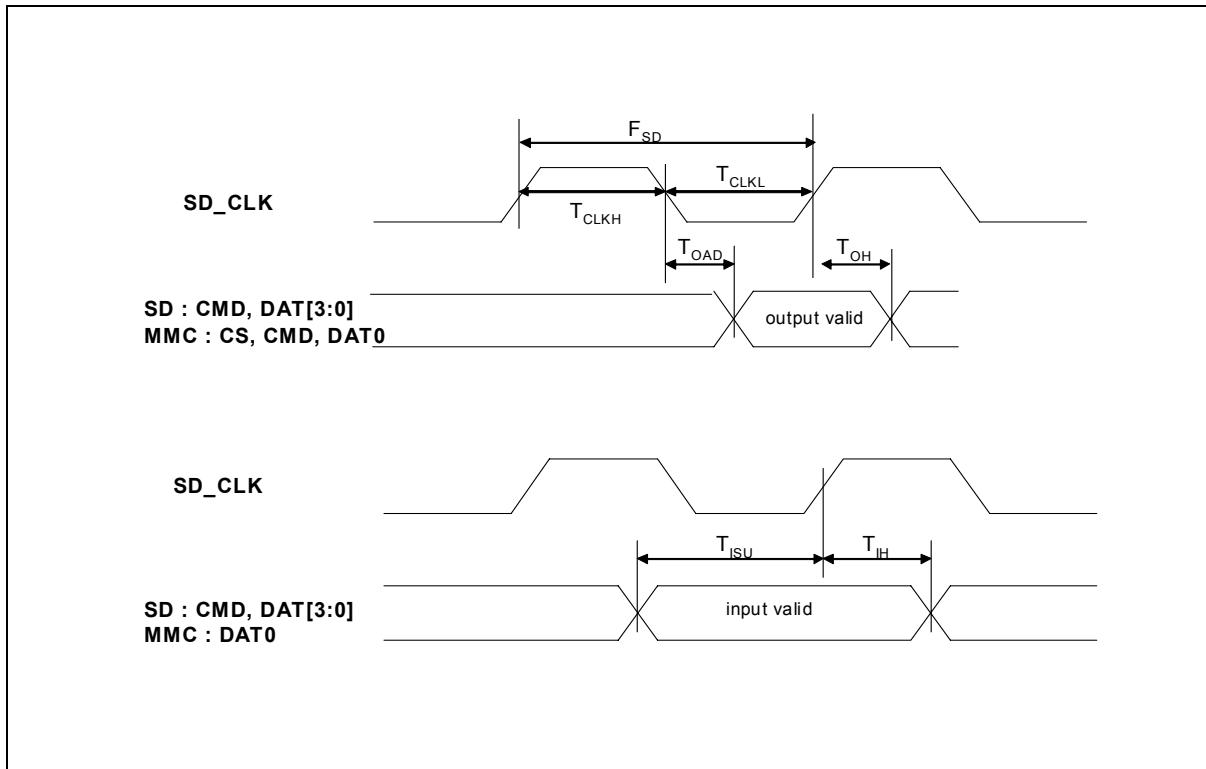


Figure 5-6 SD/MMC Host Interface Timing Diagram

Table 5-8 SD/MMC Host Interface Timing

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$F_{SD}$	SD/MMC Clock Frequency	Identification Mode	0	400	KHz
$F_{SD}$	SD/MMC Clock Frequency	Data Transfer Mode	0	25	MHz
$T_{CLKH}$	SD/MMC Clock High Time		10	---	ns
$T_{CLKL}$	SD/MMC Clock Low Time		10	---	ns
$T_{ISU}$	CMD & Data Input Setup Time		5	---	ns
$T_{IH}$	CMD & Data Input Hold Time		5	---	ns
$T_{OAD}$	Output Active Delay (Falling Edge)		---	14	ns
$T_{OH}$	Output Hold Time		20	---	ns

### 5.3.7 NAND Flash Memory Interface AC Characteristics

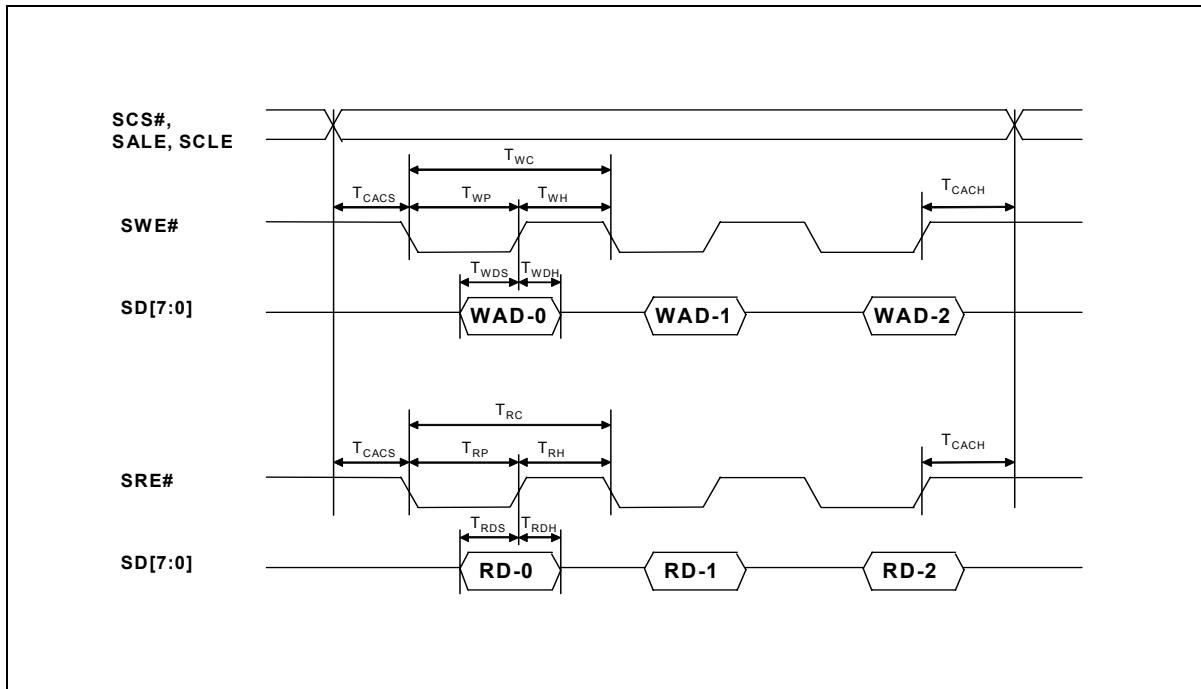


Figure 5-7 NAND Flash Memory Interface Timing Diagram

Table 5-9 NAND Flash Memory Interface Timing

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
T <sub>CACS</sub>	SCS#, SALE, SCLE Setup Time before SWE#, SRE# Low	20	---	ns
T <sub>CACH</sub>	SCS#, SALE, SCLE Hold Time after SWE#, SRE# High	40	---	ns
T <sub>WP</sub>	Write Pulse Width	40	---	ns
T <sub>WH</sub>	SWE# High Time	20	---	ns
T <sub>WC</sub>	Write Cycle Time	80	---	ns
T <sub>WDS</sub>	Write Data Output Setup Time	30	---	ns
T <sub>WDH</sub>	Write Data Output Hold Time	20	---	ns
T <sub>RP</sub>	Read Pulse Width	40	---	ns
T <sub>RH</sub>	SRE# High Time	20	---	ns
T <sub>RC</sub>	Read Cycle Time	80	---	ns
T <sub>RDS</sub>	Read Data Input Setup Time	30	---	ns
T <sub>RDH</sub>	Read Data Input Hold Time	20	---	ns

### 5.3.8 Audio I2S Interface AC Characteristics

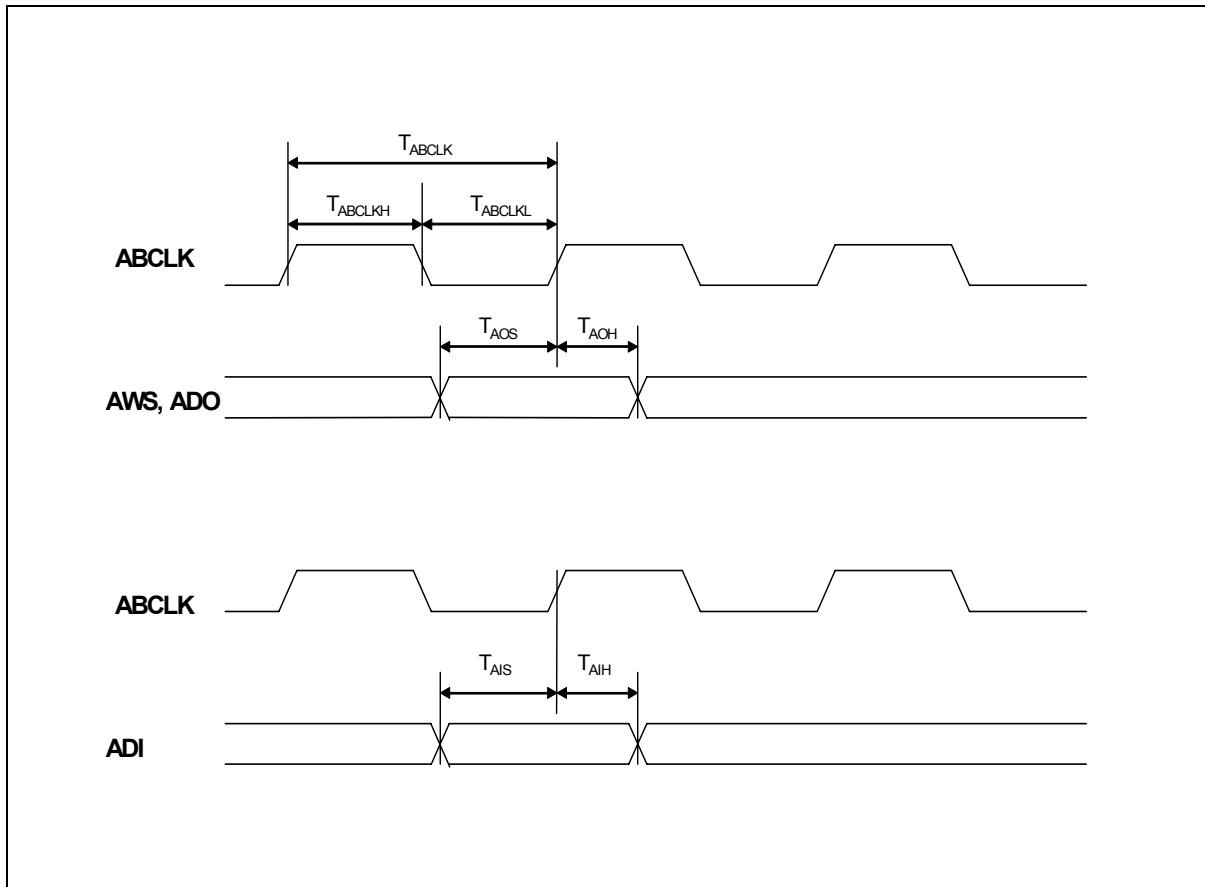


Figure 5-8 Audio I2S Interface Timing Diagram

**Table 5-10** Audio I2S Interface Timing

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
$T_{ABCLKH}$	Audio Bit Clock Output High Time	16	---	ns
$T_{ABCLL}$	Audio Bit Clock Output Low Time	16	---	ns
$T_{ABCLK}$	Audio Bit Clock Output Cycle Time	40	---	ns
$T_{AOS}$	Audio Data Output Setup Time	8	---	ns
$T_{AOH}$	Audio Data Output Hold Time	8	---	ns
$T_{AIS}$	Audio Data Input Setup Time	8	---	ns
$T_{AIH}$	Audio Data Input Hold Time	8	---	ns

### 5.3.9 Host Universal Synchronous Serial Interface AC Characteristics

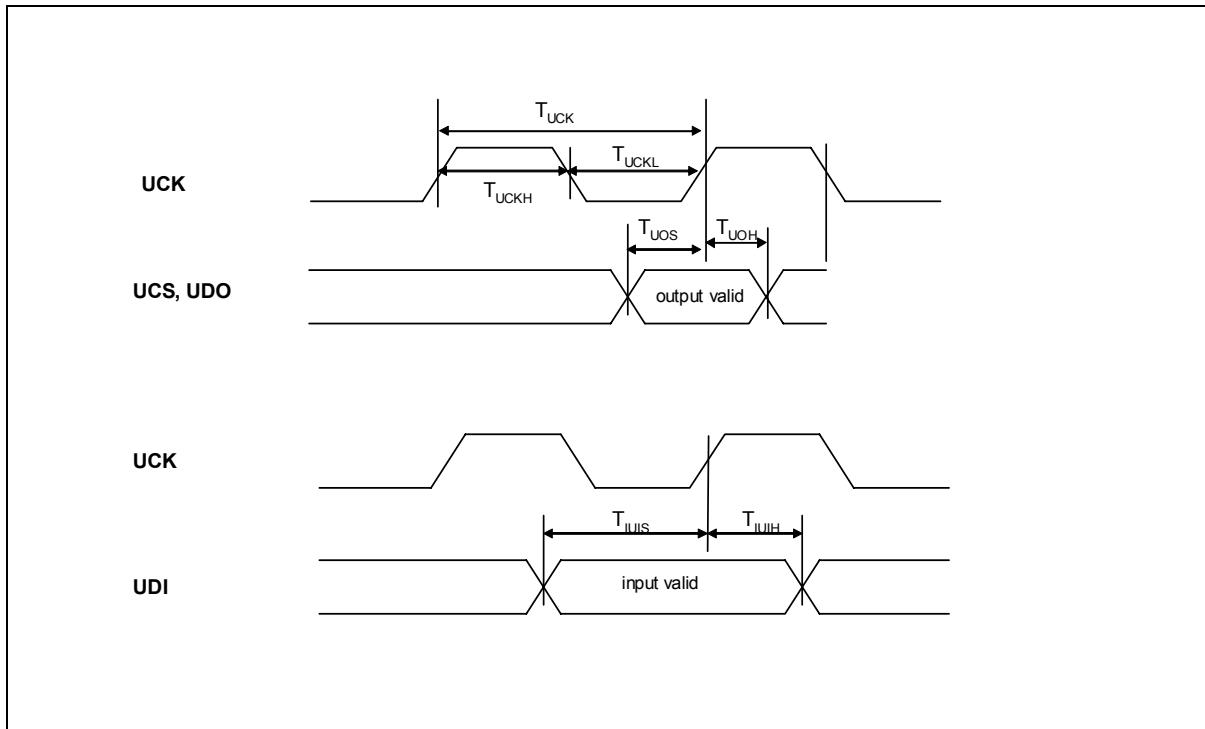


Figure 5-9 Universal Synchronous Serial Interface Timing Diagram

**Table 5-11 Host Universal Synchronous Serial Interface Timing**

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
T <sub>CLKH</sub>	Clock Output High Time	0.4	---	SCLK
T <sub>CLKL</sub>	Clock Output Low Time	0.4	---	SCLK
T <sub>CLK</sub>	Clock Cycle Time	1.0	---	SCLK
T <sub>UOS</sub>	UCS#, UDO Output Setup Time	0.3	---	SCLK
T <sub>UOH</sub>	UCS#, UDO Output Hold Time	0.3	---	SCLK
T <sub>UIS</sub>	UDI Input Setup Time	0.3	---	SCLK
T <sub>UIH</sub>	UDI Input Hold Time	0.3	---	SCLK

**Note:** SCLK = 4 \* PCLK (APB Clock, the frequency of this clock is specified by Clock Divider Register-0 & 1)



## 5.3.10 USB Transceiver AC Characteristics

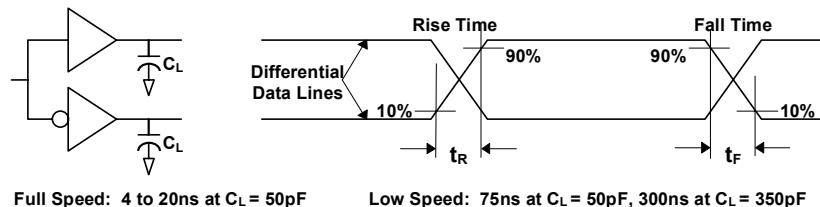


Figure 5-10 Data Signal Rise and Fall Time

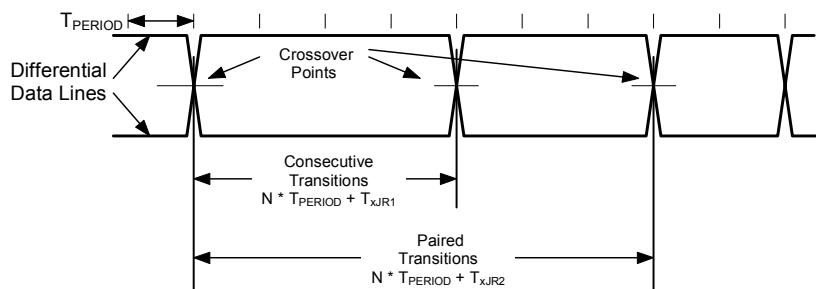


Figure 5-11 Differential Data Jitter

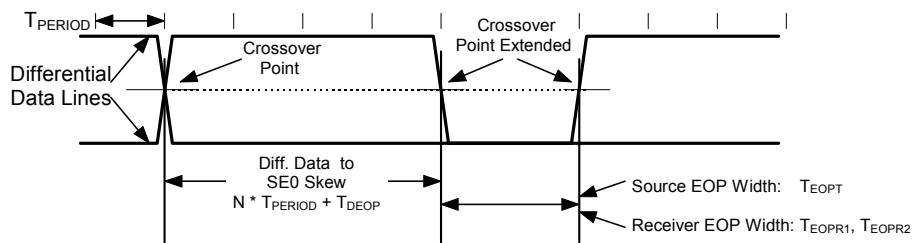


Figure 5-12 Differential to EOP Transition Skew and EOP Width

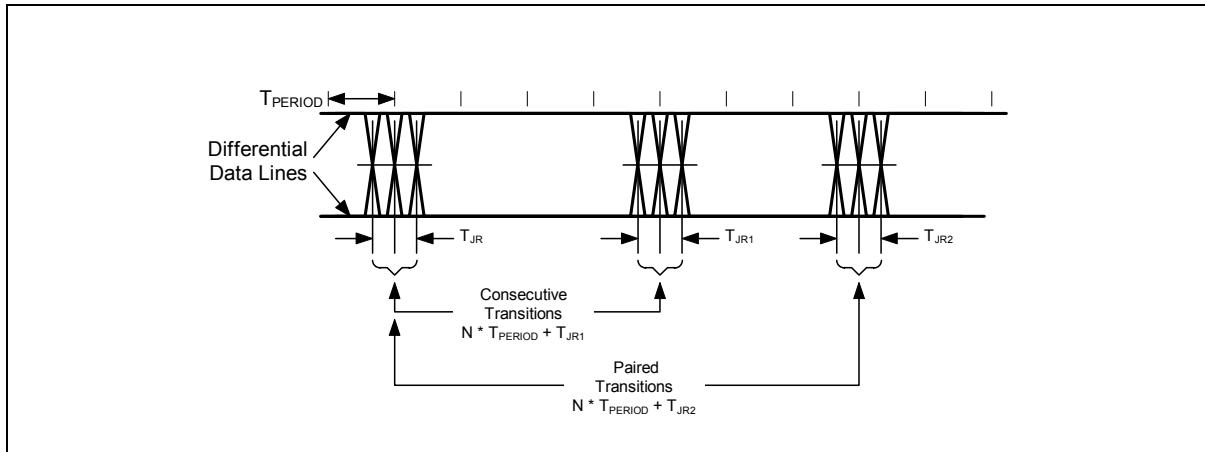


Figure 5-13 Receiver Jitter Tolerance

**Table 5-12 USB Transceiver AC Characteristics**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$T_R$	Rise Time	$CL = 50 \text{ pF}$	4	20	ns
$T_F$	Fall Time	$CL = 50 \text{ pF}$	4	20	ns
$T_{RFM}$	Rise/Fall Time Matching		90	110	%
$T_{DRATE}$	Full Speed Data Rate	Average bit rate (12 Mb/s $\pm 0.25\%$ )	11.97	12.03	Mbps
$T_{DJ1}$	Source Differential Driver Jitter To Next Transition		-3.5	3.5	ns
$T_{DJ2}$	For Paired Transitions		-4.0	4.0	ns
$T_{EOPT}$	Source EOP Width		160	175	ns
$T_{DEOP}$	Differential to EOP Transition Skew		-2	5	ns
$T_{JR1}$	Receiver Data Jitter Tolerance To Next Transition		-18.5	18.5	ns
$T_{JR2}$	For Paired Transitions		-9	9	ns
$T_{EOPR1}$	EOP Width at Receiver Must Reject as EOP		40		ns
$T_{EOPR2}$	Must Accept as EOP		82		ns



## 5.4 Audio Interface (ADC) Characteristics

### 5.4.1 Recommend Operation Conditions

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Digital Supply Range	ADO_DVDD	1.1	1.2	1.3	V
Analog Supply Range	AVDD	2.5	3.0	3.6	V
Ground	DVSS, AVSS		0		V
Temperature	TA	-20		85	°C

### 5.4.2 Electrical Characteristics

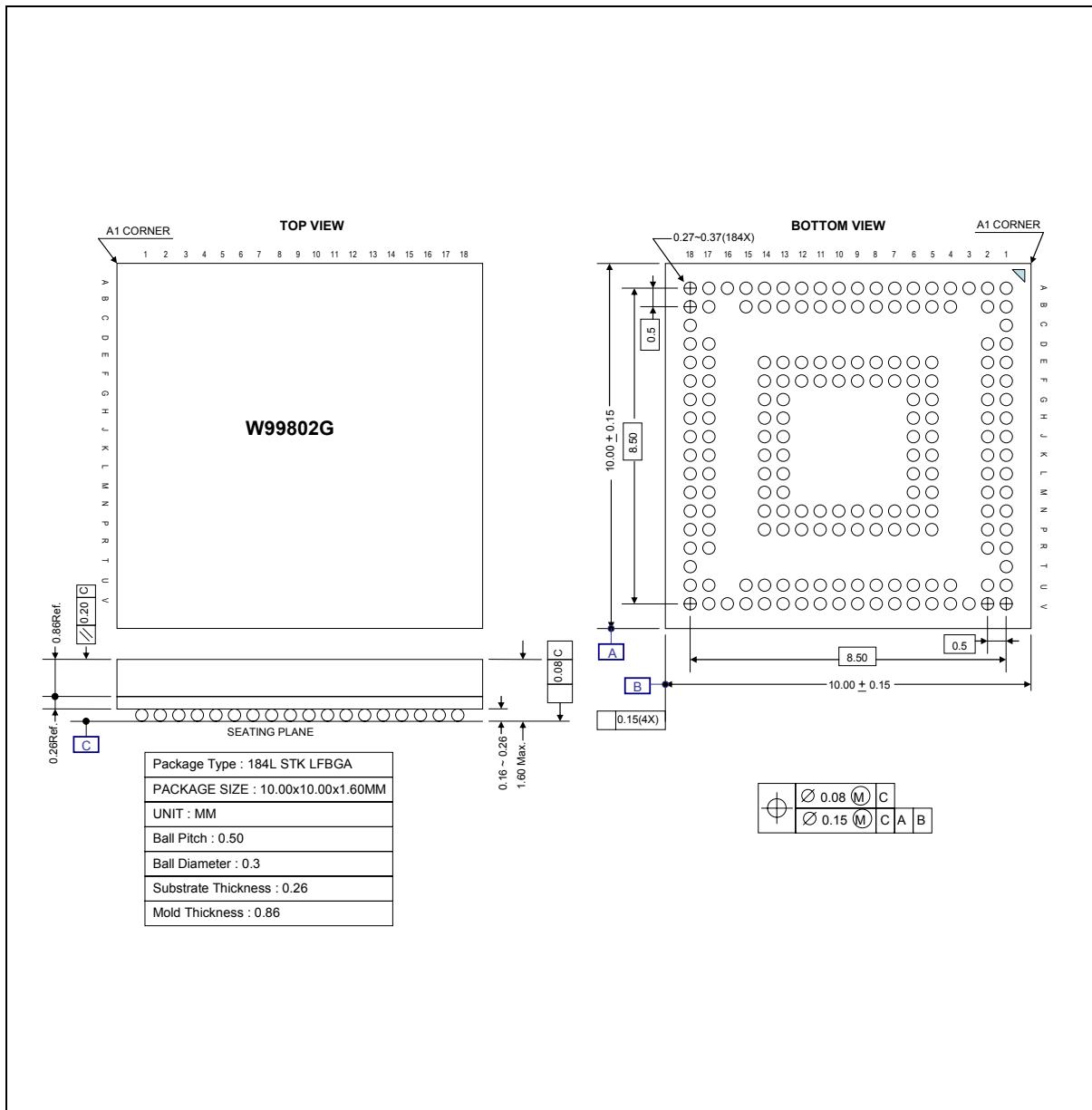
Conditions: DVDD = 1.2V, AVDD = 2.7V, TA = 30°C, 1KHz Signal, fs = 48 KHz, 16-bit audio data.

PARAMETER	SYM.	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>ADC : Analog Input (MIC_IN)</b>						
Full Scale Input Signal Level (for ADC 0dB Input at 0dB Gain)	V <sub>INFS</sub>	AVDD = 2.5V		0.707		V <sub>rms</sub>
Input Resistance			11.2		44.8	Kohm.
Input Capacitance				10		pf
Signal to Noise Ratio	SNR			70		dB
Dynamic Range			90	95		dB
Total Harmonic Distortion	THD			70		dB
<b>Analog Reference Level</b>						
Reference Voltage	VREFC		-3%	1.2	+3%	V
<b>Microphone Bias</b>						
Bias Voltage	V <sub>MICBIAS</sub>	3mA load current	-5%	0.9* AVDD	+5%	V
Bias Current Source	I <sub>MICBIAS</sub>				3	mA

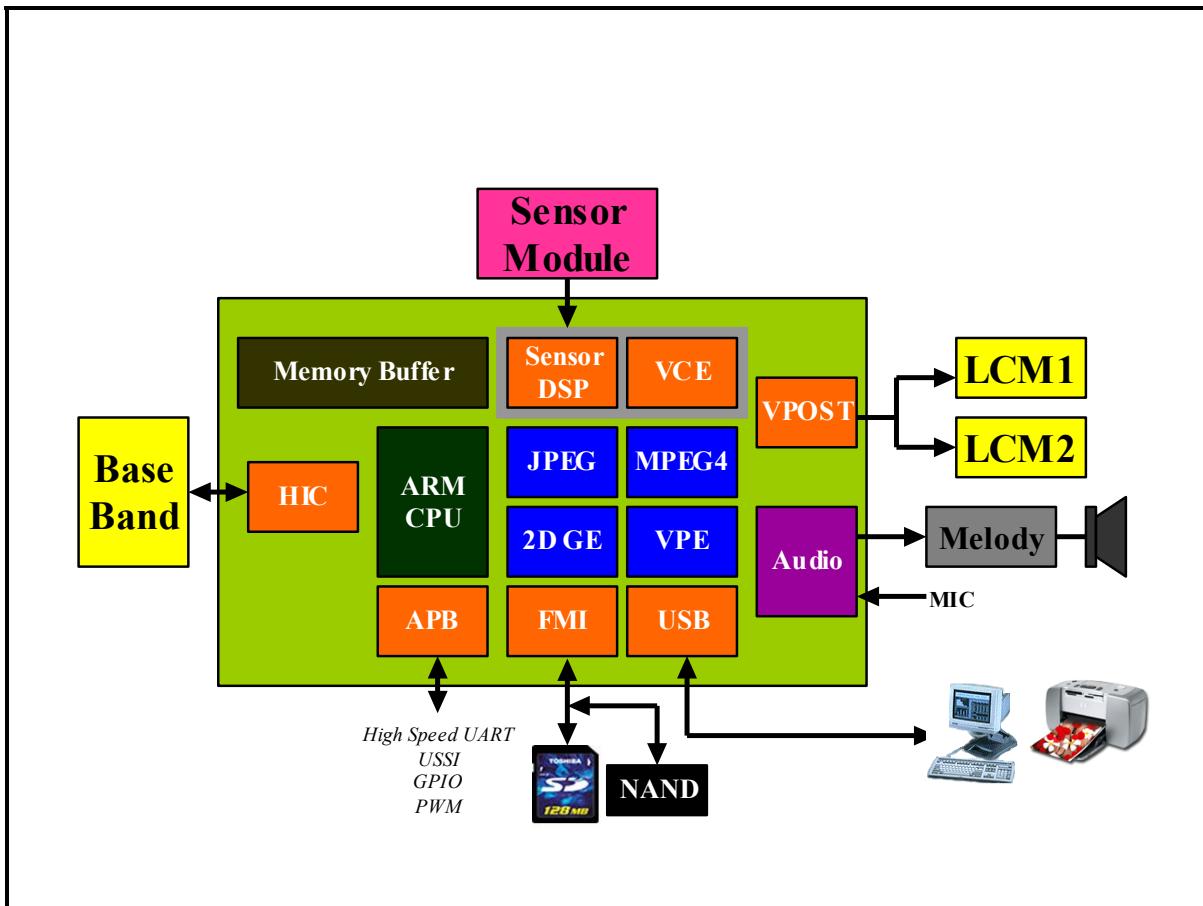


## 6. PACKAGE DIMENSION

**W99802G Package Outline (184L STK LFBGA)**



## 7. W99802G APPLICATION DIAGRAM





## 8. REVISION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
A0	Mar. 3, 2006		Public Edition

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**Headquarters**  
No. 4, Creation Rd. III,  
Science-Based Industrial Park,  
Hsinchu, Taiwan  
TEL: 886-3-5770066  
FAX: 886-3-5665577  
<http://www.winbond.com.tw/>

**Taipei Office**  
9F, No.480, Rueiguang Rd.,  
Neihu District, Taipei, 114,  
Taiwan, R.O.C.  
TEL: 886-2-8177-7168  
FAX: 886-2-8751-3579

**Winbond Electronics Corporation America**  
2727 North First Street, San Jose,  
CA 95134, U.S.A.  
TEL: 1-408-9436666  
FAX: 1-408-5441798

**Winbond Electronics Corporation Japan**  
7F Daini-ueno BLDG, 3-7-18  
Shinyokohama Kohoku-ku,  
Yokohama, 222-0033  
TEL: 81-45-4781881  
FAX: 81-45-4781800

**Winbond Electronics (Shanghai) Ltd.**  
27F, 2299 Yan An W. Rd. Shanghai,  
200336 China  
TEL: 86-21-62365999  
FAX: 86-21-62365998

**Winbond Electronics (H.K.) Ltd.**  
Unit 9-15, 22F, Millennium City,  
No. 378 Kwun Tong Rd.,  
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TEL: 852-27513100  
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